BRIOCEAN

Briocean Quality Control Center

With a combined space of around **1,000 square meters**, over **60 professional inspection tools**, and more than **50 professional inspection engineers**, Briocean has created two top-notch quality control centers in **Shenzhen** and **Hong Kong**. The Quality Control Centers of Briocean have the ability to professionally test the physical and electronic performance of various electronic components.

Stringent Quality Inspection Process

In order to ensure that each electronic component meets the required **quality standards**, Briocean inspects, verifies, and tests them starting with the packaging. The **quality of every component** sourced is something that Briocean continues to pay close attention to.

Labeling and Packaging Verification

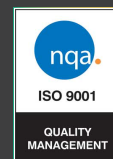**01 TIER**

Visual, Marking Inspection

02 TIER

Function, Reliability Testing

03 TIER

Find out more at:
www.briocean.com

marketing@briocean.com

10 Professional Testing Services

Visual Inspection
Conduct a thorough examination of the appearance of electronic components, such as grinding, renovation, and pin marks of the mold, and check to see if the screen-printing information matches the original label and the coding rules are in accordance with the specification's descriptions of appearance size, reliability, and PCN (whether it is EOL).

MCU Programming Test
Before validating that the chip programming function is operating properly, engineers need to check and verify that the chips received from the suppliers have not been programmed or configured and are in their factory default settings.

Burn-in Test
To preserve the chip from humid conditions, professional baking and vacuum packaging may be required in order to keep the solder reflow temperature within the range to retain the chip's availability and liability.

Decapsulation
Provide a decapsulation service by completely removing the die to inspect the screen printing and the logo, and then verify other pertinent information found on the die to further ascertain the quality and legitimacy of the components.

Electrical performance test of passive device
To determine whether the passive device's actual value falls within the acceptable range and to set the necessary parameters based on the datasheet.

SAM Failure Analysis
Ultrasonic scanning, which may identify interior materials of electronic components such as delamination, cracks, voids, silicon wafer tilt, and foreign contaminants, is a crucial step in the failure analysis process of electronic components.

X-RAY Non-destructive Flaw Inspection
Conduct a non-destructive and real-time analysis of the hardware component's interior, especially on the pin frame, die size, wire bonding map, holes, and ESD damage.

Electrical performance test of discrete devices
To evaluate component pin performance according to the product requirements.

Solderability Test
To determine whether a chip's pin can be soldered using the J-STD-002B standard by performing a solderability test.
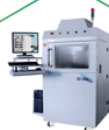
XRF Analysis
To ascertain whether the component's material complies with RoHS regulations and contains regulated elements, provide XRF testing.

High-end Testing Equipment

Leica Digital Microscope

X-Ray Non-Destructive Testing Fluoroscopy Tester
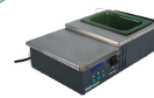
Semiconductor Testing System

Multimeter

XRF RoHS Analysis Testers

High-Temperature Test Chamber

Lead-free Tin-Melting Furnace

Hot Air Welding Platform

Intelligent Lead-Free Welding Platform

Electrostatic Tester

SMD Components Counter

Precision LCR Tester